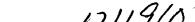


ASSIGN

102336014 -PATENTS ONLY-

SHEET



To: Honorable Commissioner of Patents and Trademarks:

Please record the attached original document(s) or copy thereof.

- 1. Name of conveying party(ies)
 - a) Chih-Ju Hung
- 2. Name and address of receiving party(ies):
 - a) Name: LSI Logic Corporation

The title of the (new) application is:

Address: 1551 McCarthy Boulevard, Milpitas, California 95035

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3.	Nature of conveyance Assignment Security Agreement Other	Merger Change of Name License Agreement	
	Execution Date: December 17, 2002		
4.	Application Number(s) or Patent Number(s): Unknown		

DIAMOND METAL-FILLED PATTERNS ACHIEVING LOW PARASITIC COUPLING CAPACITANCE

5. Please send all correspondence concerning this (these) documents to:

LSI Logic Corporation 1551 McCarthy Boulevard M/S D-106 Milpitas, CA 95035 Ph: (408) 954-4923 (Customer Number: 024319)

- 6. Total number of applications and patents involved: 1
- 7. Total fee (37 CFR 3.41): \$40.00

Enclosed

Any fees are authorized to be charged to Deposit Account No. 12-2252 (Order No. 02-5880).

8. To the best of my knowledge and belief, the foregoing information is true and correct and any

attached copy is a true copy of the original document.

Date: December 19, 2002

Elise R. Heilbrunn

Registration No. 42,649

01/13/2003 LNUELLER 00000021 122252 10327283 01 FC:8021 40.00 CH

Attorney Docket No. LSI1P209/02-5880

(Revised 12/01)

PATENT REEL: 013641 FRAME: 0436 Docket No.: 02-5880/LSI1P209

ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/WE, the undersigned, Chih-Ju Hung, do hereby sell, assign, and transfer to: LSI LOGIC CORPORATION, a corporation of Delaware, having a place of business at 1551 McCarthy Boulevard, Milpitas, California 95035, ("Assignee"), its successors, assigns, and legal representatives, the entire right, title and interest for the United States and all foreign countries, in and to any and all inventions and improvements which are disclosed in the application for United States Letters Patent,

(X)	which has been executed by	the undersigned concurrently herewith,
()	which was filed on	, 20 and assigned Application No,

and is entitled: DIAMOND METAL-FILLED PATTERNS ACHIEVING LOW PARASITIC COUPLING CAPACITANCE

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be issued in the United States and all foreign countries on said improvements; and in and to all rights of priority resulting from the filing of said United States application; and

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications to patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Name:

Chih-Ju Hung

Dated: /2/17.2002

PATENT REEL: 013641 FRAME: 0437

RECORDED: 12/19/2002